

HVD191

Silicon Epitaxial Planar PIN Diode for High Frequency Attenuator

REJ03G0015-0100Z
Rev.1.00
Apr.28.2003

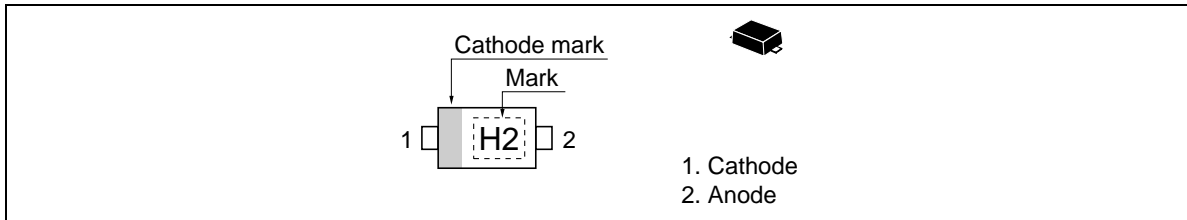
Features

- Low capacitance. ($C \leq 0.37$ pF)
- Low forward resistance. ($r_f \leq 2.5 \Omega$)
- Super small Flat Package (SFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVD191	H2	SFP

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	V_R	30	V
Forward current	I_F	100	mA
Power dissipation	P_d	150	mW
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	-55 to +125	°C

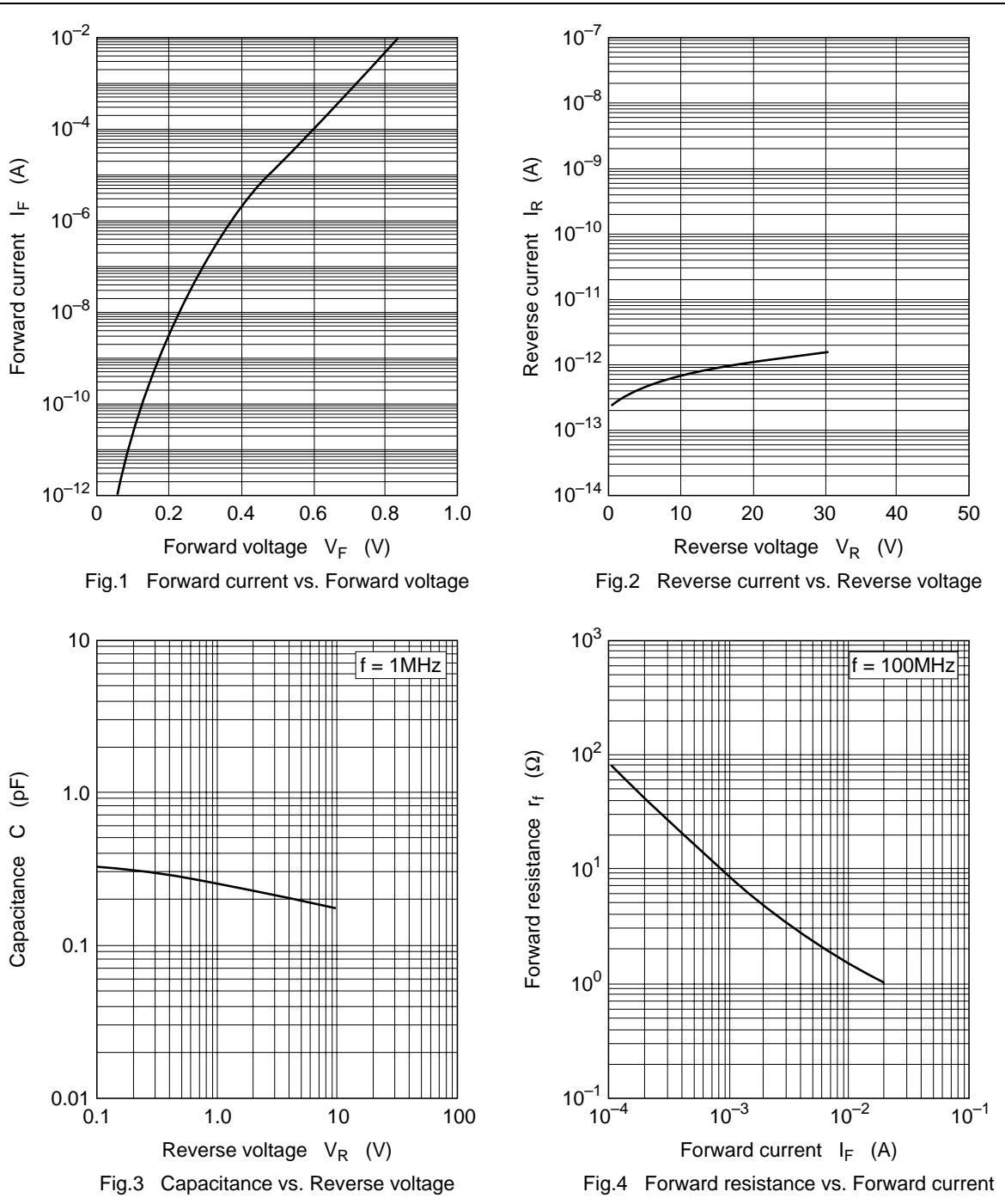
Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	V_F	—	—	1.0	V	$I_F = 10 \text{ mA}$
Reverse current	I_R	—	—	0.1	μA	$V_R = 30 \text{ V}$
Capacitance	C	—	—	0.37	pF	$V_R = 1 \text{ V}, f = 1 \text{ MHz}$
Forward resistance	r_f	—	—	2.5	Ω	$I_F = 10 \text{ mA}, f = 100 \text{ MHz}$

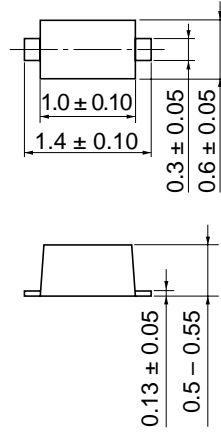
- Notes: 1. Please do not use the soldering iron due to avoid high stress to the SFP package.
2. The material of lead is exposed for cutting plane. Therefore, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

Main Characteristic



Package Dimensions

As of January, 2003
Unit: mm



Package Code	SFP
JEDEC	—
JEITA	—
Mass (reference value)	0.0010 g

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Keep safety first in your circuit designs!

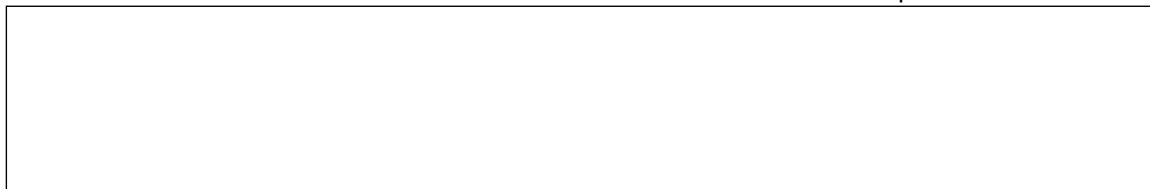
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